

MOBILITY™ RADEON™ 9100 IGP Memory Compatibility

The objective of the memory compatibility testing program is to ensure compliance of different memory modules with the MOBILITY™ RADEON™ 9100 IGP chipset. The modules are tested as to ATI specifications using industry standard testing methods. This testing is not intended to replace the normal OEM module qualification process.

The Memory Compatibility Process describes how modules can be submitted to ATI approved validation labs. Only modules which pass comprehensive testing by ATI's validation labs are listed here.

Please contact memory@ati.com should you have any questions.

MOBILITY™ RADEON™ 9100 IGP Compatible DDR333 (PC2700) 200 Pin SO-DIMM memory Modules

Buffalo					
Density	Module Part Number	CL	Loads	Type	Component Part Number
512 MB	DN333-A512M	2.5	16	32M X 16	Buffalo ME46512823MEK

Elpida					
Density	Module Part Number	CL	Loads	Type	Component Part Number
256 MB	EBD26UC6AKSA-6B	2.5	8	16M X 16	Elpida EDD2516AKTA-6B
512 MB	EBD52UD6ADSA-6B	2.5	8	32M X 16	Elpida EDD5116ADTA-6B
1 GB	EBD11UD8ABDA-6B	2.5	16	64M X 8	Elpida EDD5108ABNA-6B
1 GB	EBD11UD8ADDA-6B	2.5	16	64M X 8	Elpida EDD5108ADNA-6B

Hynix					
Density	Module Part Number	CL	Loads	Type	Component Part Number
128 MB	HYMD216M646A6-J	2.5	4	16M X 16	Hynix HY5DU561622AT-J
256 MB	HYMD232M646C6-J	2.5	8	16M X16	Hynix HY5DU561622CT-J
256 MB	HYMD232M646A8-J	2.5	8	32M X 8	Hynix HY5DU56822AT-J
256 MB	HYMD532M646A6-J	2.5	4	32M X 16	Hynix HY5DU121622AT-J
512 MB	HYMD564M646A6-J	2.5	8	32M X 16	Hynix HY5DU121622AT-J
1 GB	HYMD512M646AFS8-J	2.5	16	64M X 8	Hynix HY5DU1G822AFM-J

Micron					
Density	Module Part Number	CL	Loads	Type	Component Part Number
128 MB	MT4VDDT1664HG-335C2	2.5	4	16M X 16	Micron MT46V16M16-6T
128 MB	MT4VDDT1664HG-335C3	2.5	4	16M X 16	Micron MT46V16M16-6T
256 MB	MT8VDDT3264HG-335C2	2.5	8	32M X 8	Micron MT46V32M8-6T
256 MB	MT8VDDT3264HG-335C3	2.5	8	16M X 16	Micron MT46V16M16-6T
512 MB	MT8VDDT6464HDG-335C1	2.5	8	32M X 16	Micron MT46V32M16TG-6TC
512 MB	MT16VDDF6464HG-335C2	2.5	16	32M X 8	Micron MT46V32M8FG-6
512 MB	MT8VDDF6464HDG-335C1	2.5	8	32M X 16	Micron MT46V32M16-6T
1 GB	MT16VDDF12864HG-335C2	2.5	16	64M X 8	Micron MT46V64M8FN-6

Mosel Vitelic					
Density	Module Part Number	CL	Loads	Type	Component Part Number
256 MB	V826632G24SATG-C0	2.5	8	32M X 8	Mosel Vitelic V58C2256804SAT6
512 MB	V826664G24SASG-C0	2.5	16	32M X 8	Mosel Vitelic V58C2256804SAS6

Nanya					
Density	Module Part Number	CL	Loads	Type	Component Part Number
128 MB	NT128D64SH4BBGM-6K	2.5	4	16M X 16	Nanya NT5DS16M16BT-6K
256 MB	NT256D64SH8BAGM-6K	2.5	8	16M X 16	Nanya NT5DS16M16BT-6K
512 MB	NT512D64S8HBAFM-6K	2.5	16	32M X 8	Nanya NT5DS32M8BF-6K
512 MB	NT256D64SH8BAGM-6K	2.5	8	16M X 16	Nanya NT5DS16M16BT-6K

Powerchip Semiconductor					
Density	Module Part Number	CL	Loads	Type	Component Part Number
256 MB	AS5D8C44T-6B1T	2.5	8	32M X 8	Powerchip A2S56D40CTP

<u>Qimonda (Formerly Infineon)</u>					
Density	Module Part Number	CL	Loads	Type	Component Part Number
128 MB	HYS64D16000GDL-6-B	2.5	4	16M X 16	Infineon HYB25D256160BT-6
128 MB	HYS64D16000GDL-6-C	2.5	4	16M X 16	Infineon HYB25D256160CE-6
128 MB	HYS64D16000HDL-6-C	2.5	4	16M X 16	Infineon HYB25D256160CE-6
256 MB	HYS64D32020GDL-6-B	2.5	8	16M X 16	Infineon HYB25D256160BT-6
256 MB	HYS64D32020HDL-6-C	2.5	8	16M X 16	Infineon HYB25D256160CE-6
256 MB	HYS64D32020GDL-6-C	2.5	8	16M X 16	Infineon HYB25D256160CE-6
512 MB	HYS64D64020GBDL-6-B	2.5	16	32M X 8	Infineon HYB25D256800BC-6
512 MB	HYS64D64020GBDL-6-C	2.5	16	32M X 8	Infineon HYB25D256800CC-6
512 MB	HYS64D64020HBDL-6-B	2.5	16	32M X 8	Infineon HYB25D256800BC-6
512 MB	HYS64D64020HBDL-6-C	2.5	16	32M X 8	Infineon HYB25D256800CF-6
512 MB	HYS64D64020HBDL-6-B	2.5	8	32M X 16	Infineon HYB25D51216BE-6
1 GB	HYS64D128020GBDL-6-B	2.5	16	64M X 8	Infineon HYB25D512800BC-6

<u>Samsung</u>					
Density	Module Part Number	CL	Loads	Type	Component Part Number
64 MB	M470L0914DT0-CB3	2.5	4	8M X 16	Samsung K4H281638D-TCB3
128 MB	M470L1714DT0-CB3	2.5	8	8M X 16	Samsung K4H281638D-TCB3
128 MB	M470L1624DT0-CB3	2.5	4	16M X 16	Samsung K4H561638D-TCB3
128 MB	M470L1624FT0-CB3	2.5	4	16M X 16	Samsung K4H561638F-TCB3
256 MB	M470L3224DT0-CB3	2.5	8	16M X 16	Samsung K4H561638D-TCB3
256 MB	M470L3224FT0-CB3	2.5	8	16M X 16	Samsung K4H561638F-TCB3
256 MB	M470L3324BT0-CB3	2.5	4	32M X 16	Samsung K4H511638B-TCB3
512 MB	M470L6524BT0-CB3	2.5	8	32M X 16	Samsung K4H511638B-TCB3
512 MB	M470L6423DN0-CB3	2.5	16	32M X 8	Samsung K4H560838D-NCB3
512 MB	M470L6423EN0-CB3	2.5	16	32M X 8	Samsung K4H560838E-NCB3
1 GB	M470L2923BN0-CB3	2.5	16	64M X 8	Samsung K4H510838B-TCB3

<u>TwinMos Technologies</u>					
Density	Module Part Number	CL	Loads	Type	Component Part Number
256 MB	M2G5I08D6ATT5F081AADT	2.5	16	32M X 8	TwinMos TMD7608F8E60D

<u>Viking Interworks</u>					
Density	Module Part Number	CL	Loads	Type	Component Part Number
512 MB	VI4DU646428DBK	2.5	16	32M X 8	Samsung K4H560838D-NCB3
1 GB	VI4DU286428EBK	2.5	16	64M X 8	Micron MT46V64M8FN-5B

MOBILITY™ RADEON™ 9100 IGP
Compatible DDR400 (PC3200) 200 Pin SO-DIMM memory Modules

<u>Hynix</u>					
Density	Module Part Number	CL	Loads	Type	Component Part Number
128 MB	HYMD216M646C6-D43	3	4	16M X 16	Hynix HY5DU561622CT-D43
256 MB	HYMD232M646A6-D43	3	4	32M X 16	Hynix HY5DU121622AT-D43
256 MB	HYMD232M646A6-D43	3	8	16M X 16	Hynix HY5DU561622AT-D4
256 MB	HYMD232M646C6-D43	3	8	16M X 16	Hynix HY5DU561622CT-D43
512 MB	HYMD564M646A6-D43	3	8	32M X 16	Hynix HY5DU121622AT-D43

<u>Kingston Technology</u>					
Density	Module Part Number	CL	Loads	Type	Component Part Number
128 MB	KVR400X64SC3A/128	3	4	16M X 16	Micron MT46V16M16TG-5B

<u>Micron</u>					
Density	Module Part Number	CL	Loads	Type	Component Part Number
128 MB	MT8VDDT166HG-403B2	3	8	16M X 8	Micron MT46V16M8
128 MB	MT4VDDT1664HG-40BC3	3	4	16M X 16	Micron MT46V16M16
256 MB	MT8VDDT3264HDG-40BC3	3	8	16M X 16	Micron MT46V16M16
512 MB	MT8VDDT6464HDG-40BC1	3	8	32M X 16	Micron MT46V32M16TG-5BC

<u>Nanya</u>					
Density	Module Part Number	CL	Loads	Type	Component Part Number
256 MB	NT256D64SH8BAGM-5T	3	8	16M X 16	Nanya NT5DS16M16BT-5T

<u>Qimonda</u> (Formerly <u>Infineon</u>)					
Density	Module Part Number	CL	Loads	Type	Component Part Number
256 MB	HYS64D32020GDL-5-B	3	8	16M X 16	Infineon HYB25D256160BT-5
512 MB	HYS64D64020GBDL-5-B	3	16	32M X 8	Infineon HYB25D256800BC-5
512 MB	HYS64D64020HBDL-6-C	2.5	8	32M X 16	Infineon HYB25D51216BE-6

Samsung					
Density	Module Part Number	CL	Loads	Type	Component Part Number
128 MB	M470L1624DT0-CCC	3	4	16M X 16	Samsung K4H561638D-TCCC
128 MB	M470L1624FT0-CCC	3	4	16M X 16	Samsung K4H561638F-TCCC
256 MB	M470L3223DT0-CC4	3	8	32M X 8	Samsung K4H560838D-TCC4
256 MB	M470L3224FT0-CCC	3	8	16M X 16	Samsung K4H561638F-TCCC
512 MB	M470L6423ENO-CCC	3	16	32M X 8	Samsung K4H560838E-NCCC
1 GB	M470L2923BN0-CCC	3	16	64M X 8	Samsung K4H510838B- TCCC

Viking Interworks					
Density	Module Part Number	CL	Loads	Type	Component Part Number
512 MB	VI4DU646428DBP	3	16	32M X 8	Samsung K4H560838E-GCCC
1GB	VI4DU286428EBP	3	16	64M X 8	Micron MT46V64M8FN-5B